

IN THE CLAIMS

- 1 (Original). A package for an electronic device comprising:
a substrate;
an integrated circuit die mounted on said substrate; and
a charge pump including a passive component mounted on said die and
electrically coupled to said die, wherein the extension of said component from said die is less
than or equal to 16 mils.
- 2 (Original). The package of claim 1 including a ball grid array with multiple solder
balls attached to said substrate.
- 3 (Original). The package of claim 2 wherein said component is adhesively attached to
said die.
- 4 (Original). The package of claim 3 wherein said adhesive attachment is user-
dispensed epoxy.
- 5 (Original). The package of claim 3 wherein said component and said die are
electrically connected to said substrate using wire bonds.
- 6 (Original). The package of claim 1 wherein said component is an inductor.
- 7 (Original). The package of claim 1 wherein said component is a capacitor.
- 8 (Original). The package of claim 1 wherein said package is a molded array package.
- 9 (Original). The package of claim 1 wherein said package uses Power Supply In
Package technology.

Claims 10-16 (Canceled).

17 (Original). A method comprising:

- forming a substrate;
- mounting an integrated circuit die on said substrate; and
- forming a package with a charge pump coupled to said die in said package; and
- mounting a passive component on said die and electrically coupling said component to said die, so that the extension of said component from said die is less than or equal to 16 mils.

18 (Original). The method of claim 17 including attaching a ball grid array with multiple solder balls to said substrate.

19 (Original). The method of claim 18 including adhesively attaching said component to said die.

20 (Original). The method of claim 19 including using user-dispensed epoxy to adhesively attach said component.

21 (Original). The method of claim 20 including using wirebonds to electrically connect said component to said substrate and said die to said substrate.

22 (Original). The method of claim 17 including forming a molded array package.

23 (Original). The method of claim 17 including using Power Supply In Package technology.

Claims 24-28 (Canceled).